TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSII)

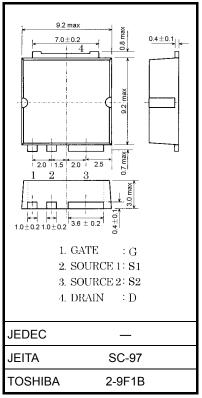
2SK3389

Switching Regulator and DC-DC Converter Applications Motor Drive Applications

- Low drain-source ON resistance: $RDS(ON) = 3.8 \text{ m}\Omega$ (typ.)
- High forward transfer admittance: $|\,Y_{\rm fs}\,|$ = 70 S (typ.)
- Low leakage current: $I_{DSS} = 100 \ \mu A (V_{DS} = 30 \ V)$
- Enhancement mode: V_{th} = 2.0 to 4.0 V (V_{DS} = 10 V, I_D = 1 mA)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	30	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)		V _{DGR}	30	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	۱ _D	75	А	
	Pulse (Note 1)	I _{DP}	300	A	
Drain power dissipation	n (Tc = 25°C)	PD	125	W	
Single pulse avalanche energy (Note 2)		E _{AS}	731	mJ	
Avalanche current		I _{AR}	75	А	
Repetitive avalanche energy (Note 3)		E _{AR}	12.5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	–55 to 150	°C	



Weight: 0.74 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.00	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

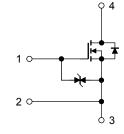
Note 2: V_DD = 25 V, T_{ch} = 25°C (initial), L = 95 $\mu\text{H},$ I_AR = 75 A, R_G = 25 Ω

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

Notice:

Please use the S1 pin for gate input signal return. Make sure that the main current flows into the S2 pin.



Electrical Characteristics (Note 4) (Ta = 25°C)

Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS}=\pm 25~V,~V_{DS}=0~V$	_		±10	μA
Drain cut-off current		I _{DSS}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_		100	μA
Drain-source breakdown voltage		V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	30		_	V
Gate threshold voltage		V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	2.0		4.0	V
Drain-source ON resistance		R _{DS (ON)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 38 \text{ A}$		3.8	5.0	mΩ
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 38 \text{ A}$	35	70	_	S
Input capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	3530	_	pF
Reverse transfer capacitance		C _{rss}		_	570		
Output capacitance		C _{oss}		_	1870		
Switching time	Rise time	tr	$V_{GS} \stackrel{10}{}_{0}V \int I_{D} = 38 \text{ A}$ $V_{GS} \stackrel{10}{}_{0}V \int G \stackrel{1}{}_{C} = 0 \text{ VOUT}$ $G \stackrel{1}{}_{C} \stackrel{1}$	_	10	_	
	Turn-on time	t _{on}		_	25		
	Fall time	t _f		_	20	_	ns
	Turn-off time	t _{off}	Duty ≦ 1%, t _w = 10 μs		65	_	
Total gate charge (gate-source plus gate-drain)		Qg			62		nC
Gate-source charge		Q _{gs}	$V_{DD} \simeq 24$ V, $V_{GS} = 10$ V, $I_D = 75$ A	—	43	_	
Gate-drain ("miller") charge		Q _{gd}			19		

Note 4: Connect the S1 and S2 pins, and ground them except during switching time measurement.

Source-Drain Ratings and Characteristics (Note 5) (Ta = 25°C)

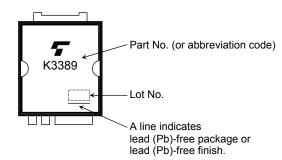
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1, Note 5)	I _{DR} 1	—	_	_	75	А
Pulse drain reverse current (Note 1, Note 5)	I _{DRP} 1	_			300	А
Continuous drain reverse current (Note 1, Note 5)	I _{DR} 2	—	_	_	1	А
Pulse drain reverse current (Note 1, Note 5)	I _{DRP} 2	—	_	_	4	А
Forward voltage (diode)	V _{DS2F}	I _{DR} 1 = 75 A, V _{GS} = 0 V	_	_	-1.5	V
Reverse recovery time	t _{rr}	$I_{DR} = 75 \text{ A}, V_{GS} = 0 \text{ V},$	_	120	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} /dt = 50 A/µs	_	180	_	nC

Note 5: I_{DR}1, I_{DRP}1: Current flowing between the drain and the S2 pin. Ensure that the S1 pin is left open. I_{DR}2, I_{DRP}2: Current flowing between the drain and the S1 pin. Ensure that the S2 pin is left open.

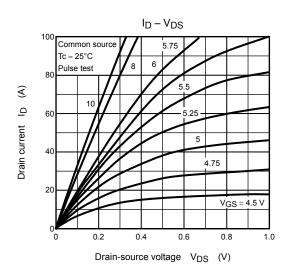
Unless otherwise specified, connect the S1 and S2 pins together, and ground them.

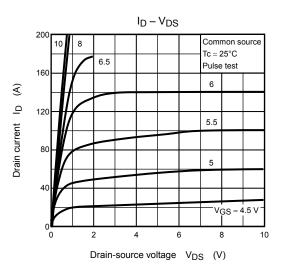


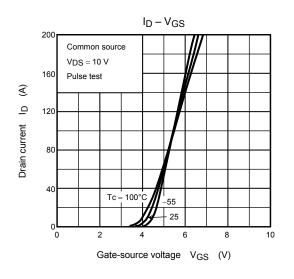
Marking

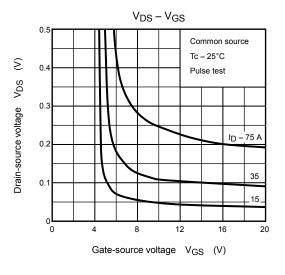


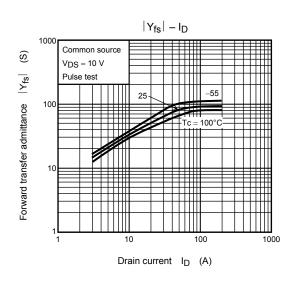
TOSHIBA

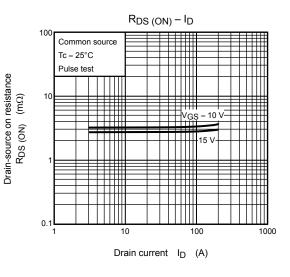


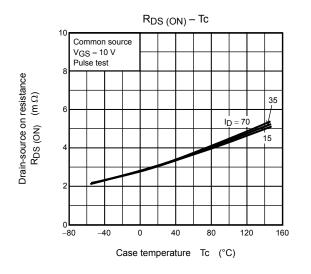


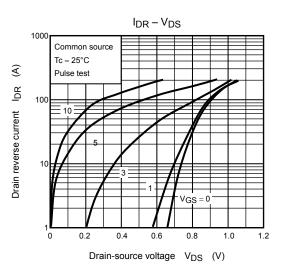


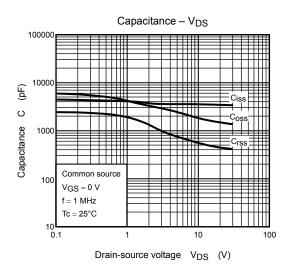


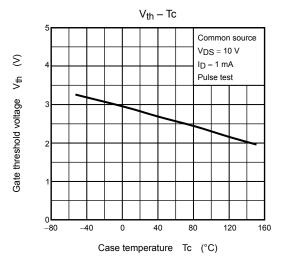


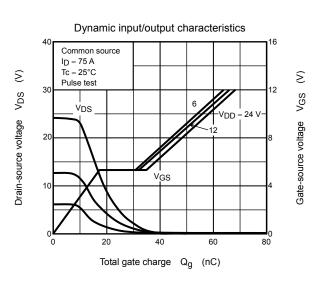


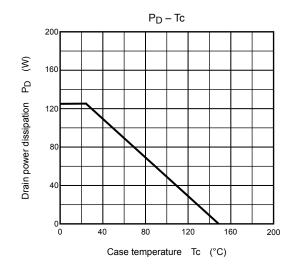


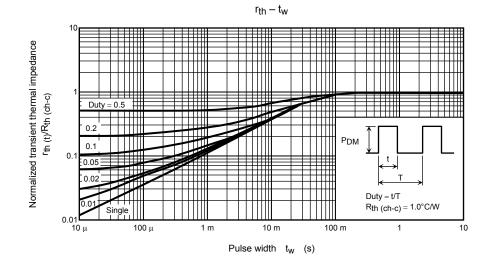


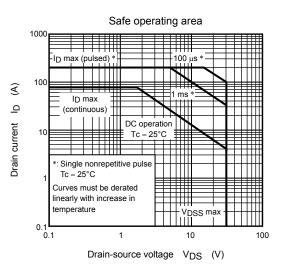


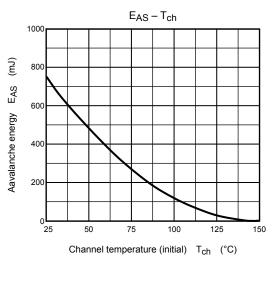


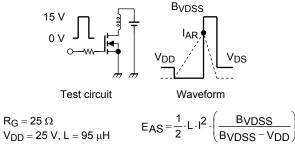












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